

ISL71090SEH25

2.5V Radiation Hardened Ultra Low Noise, Precision Voltage Reference

FN8451
Rev 5.0
May 14, 2021

The [ISL71090SEH25](#) is an ultra low noise, high DC accuracy precision voltage reference with a wide input voltage range from 4V to 30V. The ISL71090SEH25 uses the Advanced Bipolar technology to achieve 2µV_{p-p} noise at 0.1Hz with an accuracy over temperature of 0.15%.

The ISL71090SEH25 offers a 2.5V output voltage with 10ppm/°C temperature coefficient and also provides excellent line and load regulation. The device is offered in an 8 Ld flatpack package.

The ISL71090SEH25 is ideal for high-end instrumentation, data acquisition and applications requiring high DC precision where low noise performance is critical.

Applications

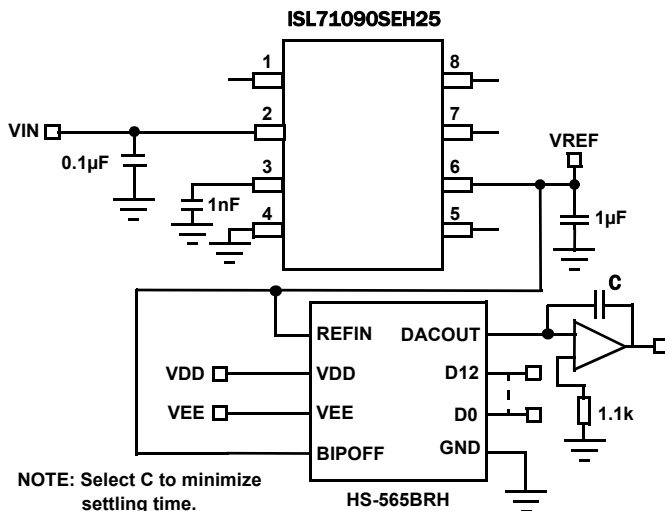
- RH voltage regulators precision outputs
- Precision voltage sources for data acquisition system for space applications
- Strain and pressure gauge for space applications

Features

- Reference output voltage **2.5V ±0.05%**
- Accuracy over temperature **±0.15%**
- Output voltage noise **2µV_{p-p} typical (0.1Hz to 10Hz)**
- Voltage accuracy over radiation **±0.175%**
- Supply current 930µA (typical)
- Tempco (box method) 10ppm/°C Max
- Output current capability 20mA
- Line regulation 8ppm/V
- Load regulation 2.5ppm/mA
- Operating temperature range..... -55°C to +125°C
- Radiation environment
 - High dose rate (50-300rad(Si)/s) **100krad(Si)**
 - Low dose rate (0.01rad(Si)/s) **50krad(Si)***
 - SET/SEL/SEB **86MeV • cm²/mg**

*Product capability established by initial characterization.

- Electrically screened to SMD [5962-13211](#)



NOTE: Select C to minimize settling time.

FIGURE 1. ISL71090SEH25 TYPICAL APPLICATION DIAGRAM

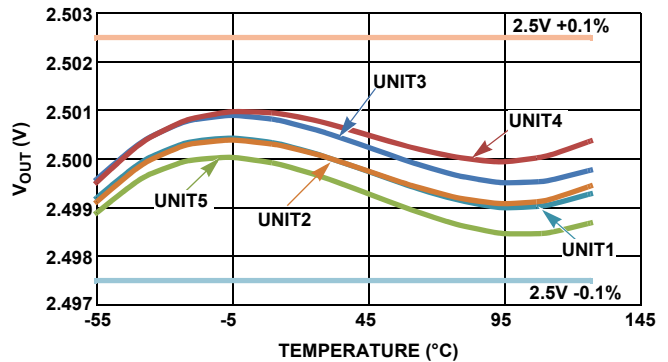


FIGURE 2. V_{OUT} vs TEMPERATURE

Ordering Information

ORDERING NUMBER (Note 2)	PART NUMBER (Note 1)	V _{OUT} OPTION (V)	RADIATION HARDNESS (Total Ionizing Dose)	PACKAGE DESCRIPTION (RoHS Compliant)	PKG. DWG. #	CARRIER TYPE	TEMP RANGE
5962R1321102VXC	ISL71090SEHVF25	2.50	HDR to 100krad(Si), LDR to 50krad(Si)	8 Ld Flatpack	K8.A	Tray	-55 to +125°C
N/A	ISL71090SEHF25/PROTO Note 4	2.50	N/A				
5962R1321102V9A	ISL71090SEHVX25 Note 3	2.50	HDR to 100krad(Si), LDR to 50krad(Si)	Die	-	-	
N/A	ISL71090SEHX25SAMPLE Notes 3, 4	2.50	N/A				
N/A	ISL71090SEH25EV1Z Note 5	Evaluation Board					

NOTES:

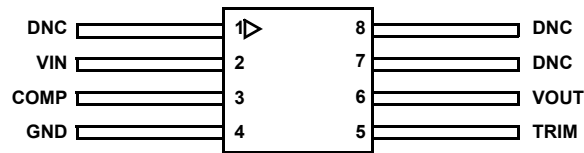
- These Pb-free Hermetic packaged products employ 100% Au plate - e4 termination finish, which is RoHS compliant and compatible with both SnPb and Pb-free soldering operations.
- Specifications for Rad Hard QML devices are controlled by the Defense Logistics Agency Land and Maritime (DLA). The SMD numbers listed must be used when ordering.
- Die product tested at T_A = + 25 °C. The wafer probe test includes functional and parametric testing sufficient to make the die capable of meeting the electrical performance outlined in "[Electrical Specifications for Die](#)" on page 6.
- The /PROTO and /SAMPLE are not rated or certified for Total Ionizing Dose (TID) or Single Event Effect (SEE) immunity. These parts are intended for engineering evaluation purposes only. The /PROTO parts meet the electrical limits and conditions across temperature specified in the DLA SMD and are in the same form and fit as the qualified device. The /SAMPLE parts are capable of meeting the electrical limits and conditions specified in the DLA SMD. The /SAMPLE parts do not receive 100% screening across temperature to the DLA SMD electrical limits. These part types do not come with a Certificate of Conformance because they are not DLA qualified devices.
- Evaluation board uses the /PROTO parts and /PROTO parts are not rated or certified for Total Ionizing Dose (TID) or Single Event Effect (SEE) immunity.

TABLE 1. KEY DIFFERENCES BETWEEN FAMILY OF PARTS

PART NUMBER	V _{OUT} (V)	TEMPCO (ppm/°C)	OUTPUT VOLTAGE NOISE (μV _{r,p})	LOAD REGULATION (ppm/mA)
ISL71090SEH12	1.25	10	1	35
ISL71090SEH25	2.5	10	2	2.5
ISL71090SEH50	5.0	10	1.1	10
ISL71090SEH75	7.5	10	1	10

Pin Configuration

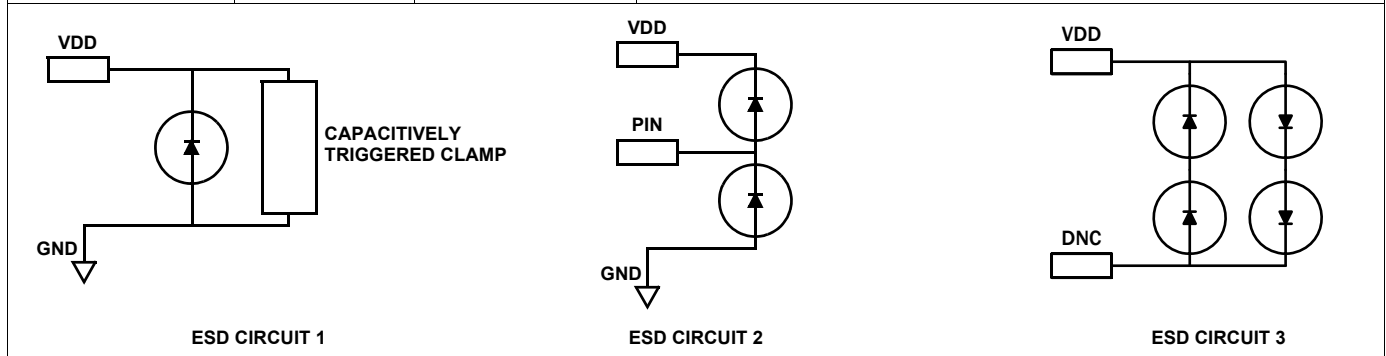
ISL71090SEH25
(8 LD FLATPACK)
TOP VIEW



NOTE: The ESD triangular mark is indicative of pin #1. It is a part of the device marking and is placed on the lid in the quadrant where pin #1 is located.

Pin Description

PIN NUMBER	PIN NAME	ESD CIRCUIT	DESCRIPTION
1, 7, 8	DNC	3	Do not connect. Internally terminated.
2	VIN	1	Input voltage connection
3	COMP	2	Compensation and noise reduction capacitor
4	GND	1	Ground connection. Also connected to the lid.
5	TRIM	2	Voltage reference trim input
6	VOUT	2	Voltage reference output



Functional Block Diagram

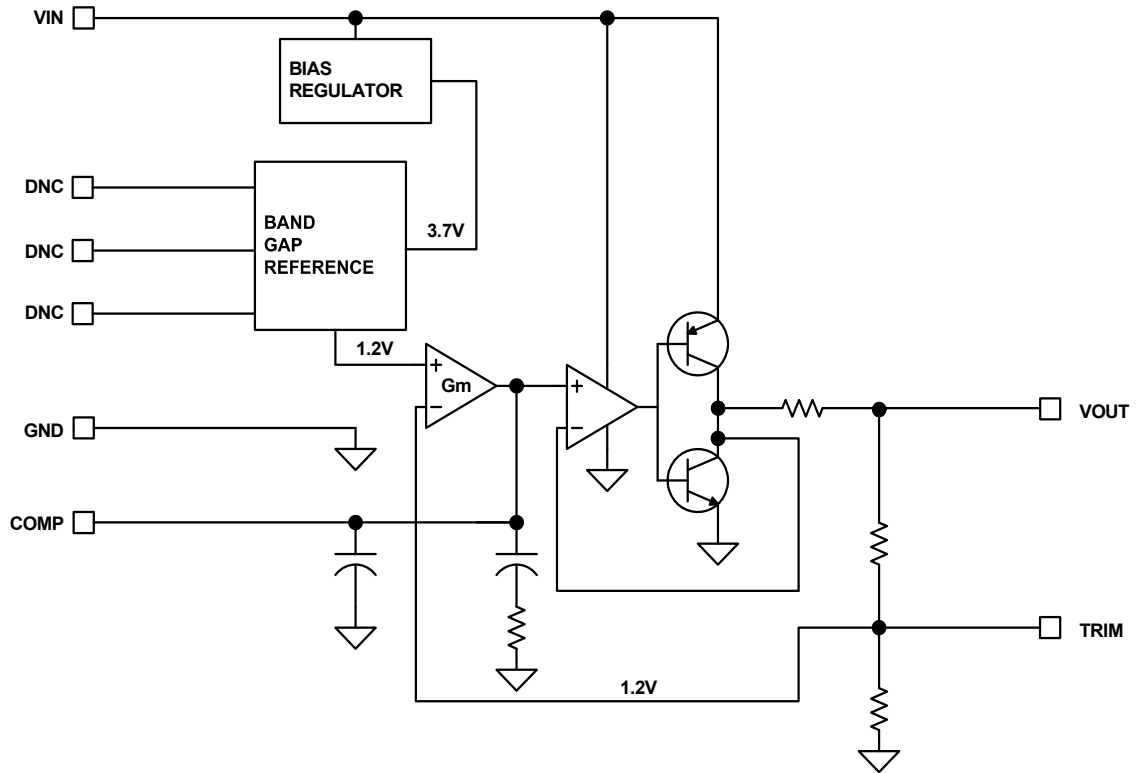


FIGURE 3. FUNCTIONAL BLOCK DIAGRAM

Absolute Maximum Ratings

Max Voltage	
V_{IN} to GND	-0.5V to +40V
V_{IN} to GND at an LET = 86MeV•cm ² /mg	-0.5V to +36V
V_{OUT} to GND (10s)	-0.5V to $V_{OUT} + 0.5V$
Voltage on any Pin to Ground	-0.5V to $+V_{OUT} + 0.5V$
Voltage on DNC Pins	No connections permitted to these pins
Input Voltage Slew Rate (Max)	0.1V/ μ s
ESD Ratings	
Human Body Model (Tested per MIL-PRF-883 3015.7)	2kV
Machine Model (Tested per JESD22-A115-A)	200V
Charged Device Model (Tested per JESD22-C101D)	750V

Thermal Information

Thermal Resistance (Typical)	θ_{JA} (°C/W)	θ_{JC} (°C/W)
8 Ld Flatpack Package (Notes 6, 7)	140	15
Storage Temperature Range	-65°C to +150°C	
Maximum Junction Temperature (T_{JMAX})	+150°C	

Recommended Operating Conditions

V_{IN}	4.0V to +30V
Temperature Range	-55°C to +125°C

CAUTION: Do not operate at or near the maximum ratings listed for extended periods of time. Exposure to such conditions can adversely impact product reliability and result in failures not covered by warranty.

NOTES:

- θ_{JA} is measured with the component mounted on a high-effective thermal conductivity test board in free air. See [TB379](#) for details.
- For θ_{JC} , the case temperature location is the center of the ceramic on the package underside.
- Product capability established by initial characterization. The "EH" version is acceptance tested on a wafer-by-wafer basis to 50krad(Si) at low dose rate.
- The output capacitance used for SEE testing is 0.1 μ F for C_{IN} and C_{OUT} .

Electrical Specifications for Flatpack $V_{IN} = 5V$, $I_{OUT} = 0mA$, $C_{OUT} = 0.1\mu F$, $COMP = 1nF$ unless otherwise specified. **Boldface limits apply after radiation at +25°C and across the operating temperature range, -55°C to +125°C without radiation, unless otherwise specified.**

PARAMETER	DESCRIPTION	TEST CONDITIONS	MIN (Note 10)	TYP	MAX (Note 10)	UNIT
V_{OUT}	Output Voltage			2.5		V
V_{OA}	V_{OUT} Accuracy at $T_A = +25^\circ C$	$V_{OUT} = 2.5V$, (Note 13)	-0.05		+0.05	%
	V_{OUT} Accuracy at $T_A = -55^\circ C$ to $+125^\circ C$	$V_{OUT} = 2.5V$, (Note 13)	-0.15		+0.15	%
	V_{OUT} Accuracy at $T_A = +25^\circ C$, Post Radiation	$V_{OUT} = 2.5V$, (Note 13)	-0.175		+0.175	%
TC V_{OUT}	Output Voltage Temperature Coefficient (Note 11)				10	ppm/°C
V_{IN}	Input Voltage Range		4		30	V
I_{IN}	Supply Current			0.930	1.280	mA
$\Delta V_{OUT}/\Delta V_{IN}$	Line Regulation	$V_{IN} = 4V$ to $30V$		8	18	ppm/V
$\Delta V_{OUT}/\Delta I_{OUT}$	Load Regulation	Sourcing: $0mA \leq I_{OUT} \leq 20mA$		20	35	ppm/mA
		Sinking: $-10mA \leq I_{OUT} \leq 0mA$		40	70	ppm/mA
V_D	Dropout Voltage (Note 12)	$I_{OUT} = 10mA$		1.1	1.7	V
I_{SC+}	Short-Circuit Current	$T_A = +25^\circ C$, V_{OUT} tied to GND		55		mA
I_{SC-}	Short-Circuit Current	$T_A = +25^\circ C$, V_{OUT} tied to V_{IN}		-61		mA
t_R	Turn-On Settling Time	90% of final value, $C_L = 1.0\mu F$, $C_C = open$		150		μs
	Ripple Rejection	$f = 120Hz$		90		dB
e_N	Output Voltage Noise	$0.1Hz \leq f \leq 10Hz$		1.9		μV_{P-P}
V_N	Broadband Voltage Noise	$10Hz \leq f \leq 1kHz$		1.6		μV_{RMS}
	Noise Density	$f = 1kHz$		50		nV/ \sqrt{Hz}
$\Delta V_{OUT}/\Delta t$	Long Term Drift	$T_A = +125^\circ C$, 1000Hrs		15		ppm

Electrical Specifications for Die $V_{IN} = 5V$, $I_{OUT} = 0mA$, $C_{OUT} = 0.1\mu F$, $COMP = 1nF$ unless otherwise specified. **Boldface limits apply after radiation at +25 °C and across the operating temperature range, -55 °C to +125 °C without radiation, unless otherwise specified.** Specifications over temperature are guaranteed but not production tested on die.

PARAMETER	DESCRIPTION	CONDITIONS	MIN (Note 10)	TYP	MAX (Note 10)	UNIT
V_{OUT}	Output Voltage			2.5		V
V_{OA}	V_{OUT} Accuracy at $T_A = +25^\circ C$	$V_{OUT} = 2.5V$, (Note 14)	-0.05		+0.05	%
	V_{OUT} Accuracy at $T_A = -55^\circ C$ to $+125^\circ C$	$V_{OUT} = 2.5V$, (Note 14)	-0.15		+0.15	%
	V_{OUT} Accuracy at $T_A = +25^\circ C$, Post Rad	$V_{OUT} = 2.5V$, (Note 14)	-0.175		+0.175	%
TC V_{OUT}	Output Voltage Temperature Coefficient (Note 11)				10	ppm/°C
V_{IN}	Input Voltage Range		4		30	V
I_{IN}	Supply Current			0.930	1.280	mA
$\Delta V_{OUT}/\Delta V_{IN}$	Line Regulation	$V_{IN} = 4V$ to $30V$		8	18	ppm/V
$\Delta V_{OUT}/\Delta I_{OUT}$	Load Regulation	Sourcing: $0mA \leq I_{OUT} \leq 20mA$		20	35	ppm/mA
		Sinking: $-10mA \leq I_{OUT} \leq 0mA$		40	70	ppm/mA
V_D	Dropout Voltage (Note 12)	$I_{OUT} = 10mA$		1.1	1.7	V

NOTES:

- Compliance to datasheet limits is assured by one or more methods: production test, characterization and/or design.
- Over the specified temperature range. Temperature coefficient is measured by the box method whereby the change in V_{OUT} is divided by the temperature range; in this case, $-55^\circ C$ to $+125^\circ C = +180^\circ C$.
- Dropout Voltage is the minimum $V_{IN} - V_{OUT}$ differential voltage measured at the point where V_{OUT} drops 1mV from $V_{IN} = \text{nominal}$ at $T_A = +25^\circ C$.
- Post-reflow drift for the ISL71090SEH25 devices can be $100\mu V$ typical based on experimental results with devices on FR4 double sided boards. The engineer must take this into account when considering the reference voltage after assembly.
- The V_{OUT} accuracy is based on die mount with Silver Glass die attach material such as "QMI 2569" or equivalent in a package with an Alumina ceramic substrate

Typical Performance Curves

$V_{IN} = 5V, V_{OUT} = 2.5V, T_A = +25^\circ C, C_{OUT} = 0.1\mu F, COMP = 1nF$ unless otherwise specified.

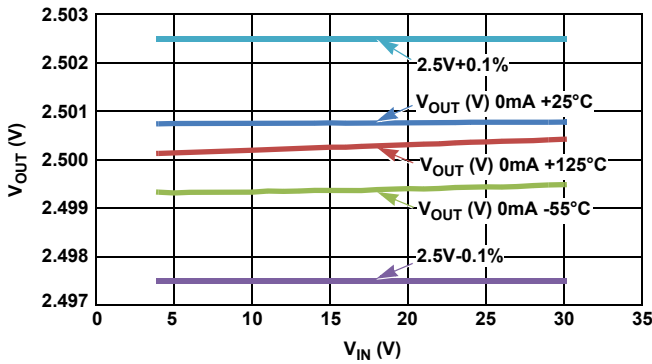


FIGURE 4. V_{OUT} ACCURACY OVER-TEMPERATURE

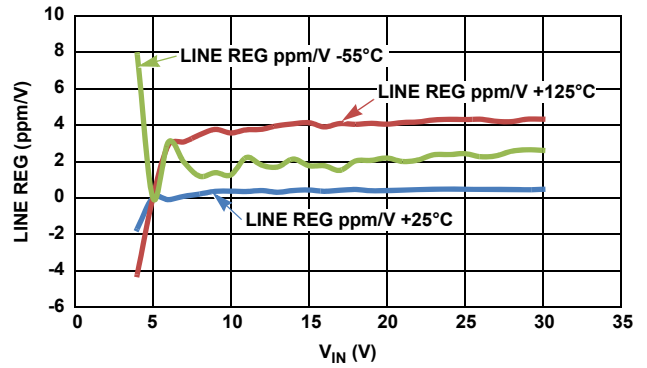


FIGURE 5. LINE REGULATION OVER-TEMPERATURE (0mA)

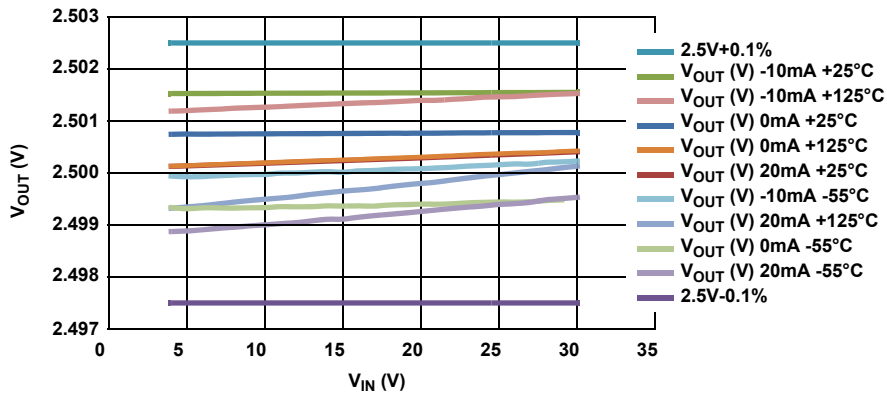


FIGURE 6. V_{OUT} vs V_{IN} AT 0mA, 20mA AND -10mA

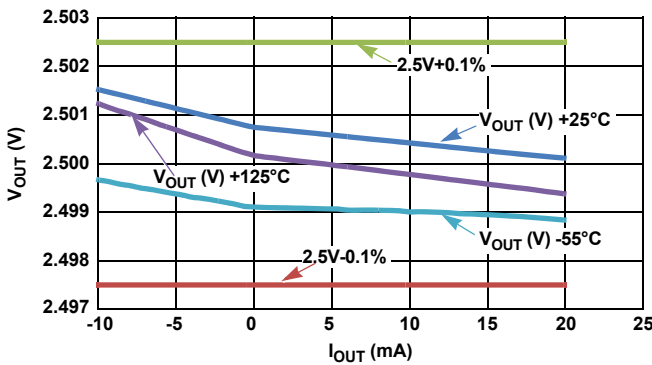


FIGURE 7. LOAD REGULATION OVER-TEMPERATURE AT $V_{IN} = 5V$ (V)

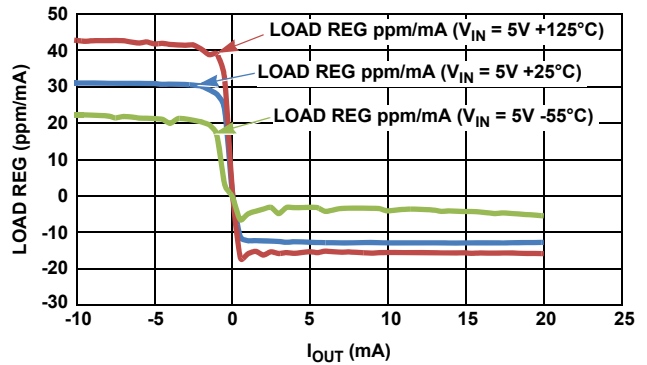


FIGURE 8. LOAD REGULATION OVER-TEMPERATURE AT $V_{IN} = 5V$ (ppm/mA)

Typical Performance Curves

$V_{IN} = 5V, V_{OUT} = 2.5V, T_A = +25^\circ C, C_{OUT} = 0.1\mu F, COMP = 1nF$ unless otherwise specified.

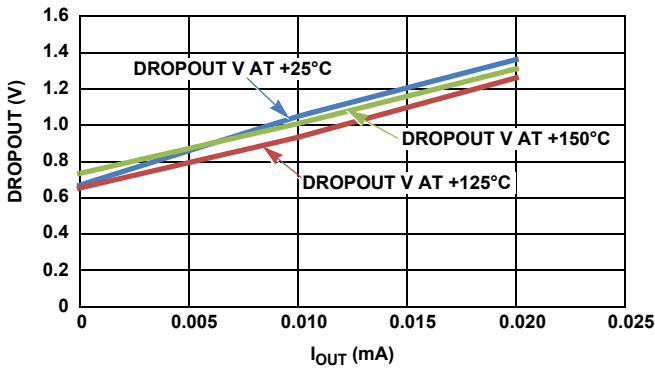


FIGURE 9. DROPOUT VOLTAGE FOR 2.5V

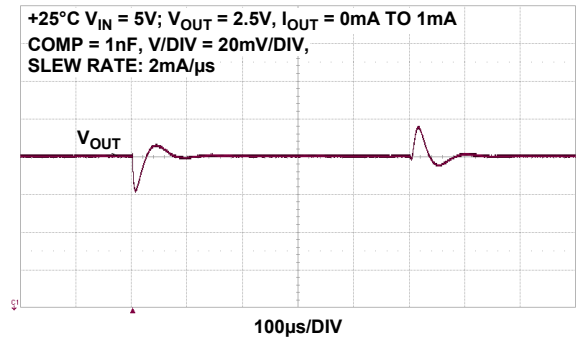


FIGURE 10. LOAD TRANSIENT (0mA TO 1mA)

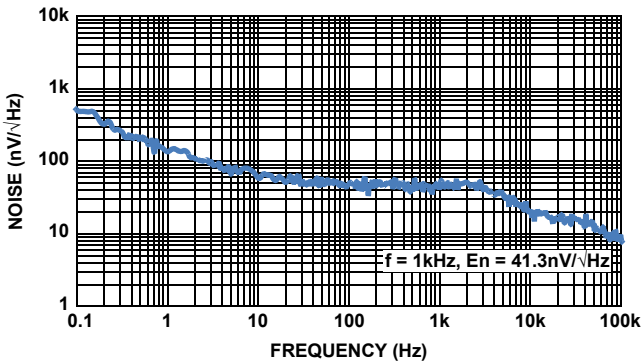


FIGURE 11. NOISE DENSITY vs FREQUENCY ($V_{IN} = 5.0V, I_{OUT} = 0mA, C_{IN} = 0.1\mu F, C_{OUT} = 1\mu F, COMP = 1nF$)

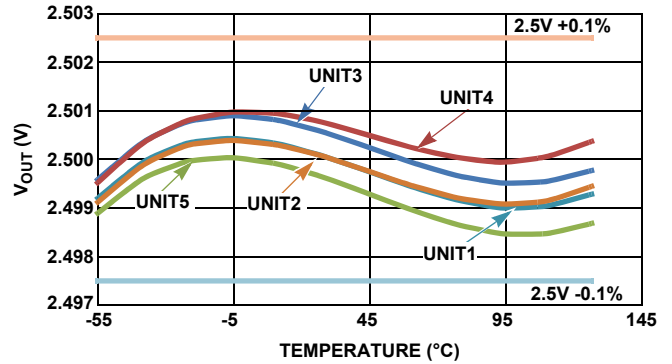


FIGURE 12. TYPICAL TEMPERATURE COEFFICIENT PLOT FOR 5 UNITS

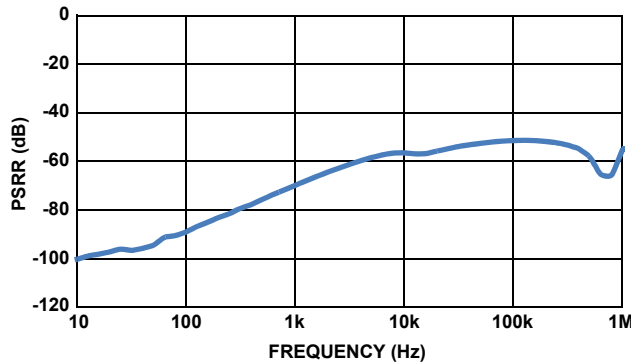


FIGURE 13. PSRR ($+25^\circ C, V_{IN} = 5V, V_{OUT} = 2.5V, I_{OUT} = 0mA, C_{IN} = C_{OUT} = 0.1\mu F, COMP = 1nF, VSIG = 300mV_{p-p}$)

Device Operation

Bandgap Precision Reference

The ISL71090SEH25 uses a bandgap architecture and special trimming circuitry to produce a temperature compensated, precision voltage reference with high input voltage capability and moderate output current drive.

Applications Information

Board Mounting Considerations

For applications requiring the highest accuracy, board mounting location should be reviewed. The device uses a ceramic flatpack package. Generally, mild stresses to the die when the Printed Circuit (PC) board is heated and cooled, can slightly change the shape. Because of these die stresses, placing the device in areas subject to slight twisting can cause degradation of reference voltage accuracy. It is normally best to place the device near the edge of a board, or on the shortest side, because the axis of bending is most limited in that location. Mounting the device in a cutout also minimizes flex. Obviously, mounting the device on flexprint or extremely thin PC material will likewise cause loss of reference accuracy.

Board Assembly Considerations

Some PC board assembly precautions are necessary. Normal output voltage shifts of typically 100 μ V can be expected with Pb-free reflow profiles or wave solder on multi-layer FR4 PC boards. Precautions should be taken to avoid excessive heat or extended exposure to high reflow or wave solder temperatures.

Noise Performance and Reduction

The output noise voltage over the 0.1Hz to 10Hz bandwidth is typically 2 μ V_{P-P} ($V_{OUT} = 2.5V$). The noise measurement is made with a 9.9Hz bandpass filter. Noise in the 10Hz to 1kHz bandwidth is approximately 1.6 μ V_{RMS} ($V_{OUT} = 2.5V$), with 0.1 μ F capacitance on the output. This noise measurement is made with a band pass filter of 990Hz. Load capacitance up to 10 μ F (with COMP) can be added but will result in only marginal improvements in output noise and transient response.

Turn-On Time

Normal turn-on time is typically 150 μ s, the circuit designer must take this into account when looking at power-up delays or sequencing.

Temperature Coefficient

The limits stated for temperature coefficient (Tempco) are governed by the method of measurement. The overwhelming standard for specifying the temperature drift of a reference is to measure the reference voltage at two temperatures, which provide for the maximum voltage deviation and take the total variation, ($V_{HIGH} - V_{LOW}$), this is then divided by the temperature extremes of measurement ($T_{HIGH} - T_{LOW}$). The result is divided by the nominal reference voltage (at $T = +25^{\circ}C$) and multiplied by 10^6 to yield ppm/ $^{\circ}C$. This is the "Box" method for specifying temperature coefficient.

Output Voltage Adjustment

The output voltage can be adjusted above and below the factory-calibrated value via the trim terminal. The trim terminal is the negative feedback divider point of the output op amp. The voltage at the trim pin is set at approximately 1.216V by the internal bandgap and amplifier circuitry of the voltage reference. The suggested method to adjust the output is to connect a 1M Ω external resistor directly to the trim terminal and connect the other end to the wiper of a potentiometer that has a 100k Ω resistance and whose outer terminals connect to V_{OUT} and ground. If a 1M Ω resistor is connected to trim, the output adjust range will be $\pm 6.3mV$. The TRIM pin should not have any capacitor tied to its output, also it is important to minimize the capacitance on the trim terminal during layout to preserve output amplifier stability. It is also best to connect the series resistor directly to the trim terminal, to minimize that capacitance and also to minimize noise injection. Small trim adjustments will not disturb the factory-set temperature coefficient of the reference, but trimming near the extreme values can.

Output Stage

The output stage of the device has a push-pull configuration with a high-side PNP and a low-side NPN. This helps the device to act as a source and sink. The device can source 20mA and sink 10mA.

Use of COMP Capacitor

The reference can be compensated for the C_{OUT} capacitors used by adding a capacitor from COMP pin to GND. See [Table 2](#) for recommended values of the COMP capacitor.

TABLE 2.

C_{OUT} (μ F)	C_{COMP} (nF)
0.1	1
1	1
10	10

SEE Testing

The device was tested under ion beam at an LET of 86MeV \cdot cm²/mg. The device did not latch-up or burn out to a VDD of 36V and at +125 $^{\circ}C$. Single Event transients were observed and are summarized in the [Table 3](#):

TABLE 3.

V_{IN} (V)	I_{OUT} (mA)	C_{OUT} (μ F)	SET (% V_{OUT})
4	5	1	-4.6
30	5	1	-4.4
30	5	10	-1.0

DNC Pins

These pins are for trimming purpose and for factory use only. Do not connect these to the circuit in any way. It will adversely effect the performance of the reference.

Package Characteristics

Weight of Packaged Device

0.31 Grams (Typical)

Lid Characteristics

Finish: Gold
 Potential: Connected to pin #4 (GND)
 Case Isolation to Any Lead: $20 \times 10^9 \Omega$ (min)

Die Characteristics

Die Dimensions

$1464\mu\text{m} \times 1744\mu\text{m}$ (58 mils x 69 mils)
 Thickness: $483\mu\text{m} \pm 25\mu\text{m}$ (19 mils \pm 1 mil)

Interface Materials

GLASSIVATION

Type: Nitrox
 Thickness: $15\text{k}\text{\AA}$

TOP METALLIZATION

Type: AlCu (99.5%/0.5%)
 Thickness: $30\text{k}\text{\AA}$

BACKSIDE FINISH

Silicon

ASSEMBLY RELATED INFORMATION

SUBSTRATE POTENTIAL

Floating

ADDITIONAL INFORMATION

WORST CASE CURRENT DENSITY

$<2 \times 10^5 \text{ A/cm}^2$

TRANSISTOR COUNT

182

PROCESS

Dielectrically Isolated Advanced Bipolar Technology- PR40

Metallization Mask Layout

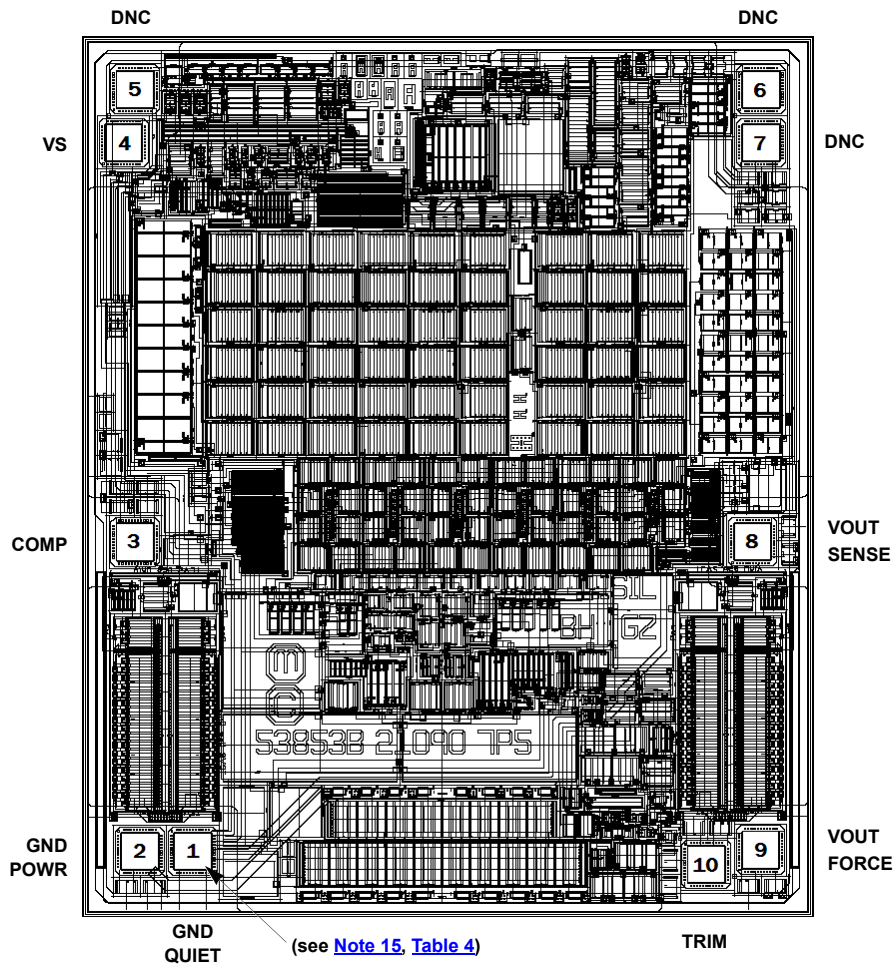


TABLE 4. DIE LAYOUT X-Y COORDINATES

PAD NAME	PAD NUMBER	X (μm)	Y (μm)	BOND WIRES PER PAD
GND PWR	2	-104	0	1
GND QUIET	1	0	0	1
COMP	3	-108	589	1
VS	4	-125	1350	1
DNC	5	-108	1452	1
DNC	6	1089	1452	1
DNC	7	1089	1350	1
VOUT SENSE	8	1072	598	1
VOUT FORCE	9	1088	1	1
TRIM	10	985	-25	1

NOTES:

15. Origin of coordinates is the centroid of GND QUIET.
 16. Bond wire size is 1 mil.

Revision History The revision history provided is for informational purposes only and is believed to be accurate, but not warranted. Please go to the web to make sure that you have the latest revision.

DATE	REVISION	CHANGE
May 14, 2021	5.0	Updated the Radiation Features bullet. Updated Ordering Information table formatting and added Notes 3, 4, and 5. Added the Transistor Count to the Assembly Related Information. Removed Related Literature and About Intersil sections.
Mar 18, 2016	4.0	-Changed title From: "Radiation Hardened Ultra Low Noise, Precision Voltage Reference" to: "2.5V Radiation Hardened Ultra Low Noise, Precision Voltage Reference" -Updated Related Literature document titles to match titles on the actual documents. -Corrected the Evaluation board part number in the Ordering Information table on page 2. -Added Table 1 on page 2. On page 5: -Changed Electrical Specification for Flatpack heading from: "Boldface limits apply over the operating temperature range, -55 °C to +125 °C and radiation." to: "Boldface limits apply after radiation at +25 °C or across the operating temperature range, -55 °C to +125 °C without radiation, unless otherwise specified." -For parameters V_{OA} (rows 2, 3, 4) in Electrical Specifications for Flatpack table added "Note 13" to Conditions column. -Removed reference to TB493 as this is not applicable to hermetic packages. On page 6: -Changed Electrical Specification for Die heading from: "Boldface limits apply over the operating temperature range, -55 °C to +125 °C and radiation." to: "Boldface limits apply after radiation at +25 °C or across the operating temperature range, -55 °C to +125 °C without radiation, unless otherwise specified." -For parameters V_{OA} (rows 2, 3, 4) in Electrical Specifications for Die table added "Note 14" to Conditions column. Updated POD K8.A to the latest revision changes are as follows: -Modified Note 2 by adding the words "...in addition to or instead of..."
Feb 27, 2014	3.0	On page 1, Under features: Added voltage accuracy over radiation with $\pm 0.175\%$ value. On page 1: Under features changed the text from accuracy over temperature and radiation to: accuracy over temperature. "Pin Description" on page 3: Under description for pin number 4 added the lid connected to ground. Electrical specifications table for "Die" on page 6 under accuracy post rad updated min from -0.152 to -0.175 and max from +0.15 to +0.175.
Sep 13, 2013	2.0	Electrical specifications table for Output Voltage (V_{OUT}) on page 5 and page 6: Removed $V_{IN} = 5V$ from conditions cell. Electrical specifications table for dropout voltage on page 5 and page 6: Changed $V_{OUT} = 2.5V$ at $10mA$ to $I_{OUT} = 10mA$. Electrical specifications table for "Flatpack" on page 5 as follow: Removed $V_{OUT} = 2.5V$ from Input Voltage Range, Line Regulation, Dropout Voltage, Output Voltage Noise, Broadband Voltage Noise, Noise Density. Electrical specifications table for "Die" on page 6 as follow: Removed $V_{OUT} = 2.5V$ from Input Voltage Range, Line Regulation, Dropout Voltage. Typical Performance Curves on page 7 added " $C_{OUT} = 0.1\mu F$, $COMP = 1nF$ " to header. Added $C_{OUT} = 0.1\mu F$, $COMP = 1nF$ to Electrical spec table on page 6. Added die sale part number to Electrical spec table on page 6. Added 1nF COMP to figure 1 on page 1. Electrical Spec on page 5: Changed $I_{OUT} = 0$ to $I_{OUT} = 0mA$. Added die sale part number to electrical spec table on page 6.
Aug 8, 2013	1.0	Page 1, Related Literature. Updated title of AN1847 from "ISL71090SEH25 Evaluation Board User's Guide" to "ISL71090SEHXX Evaluation Board User's Guide"
Jun 6, 2013	0.0	Initial Release.

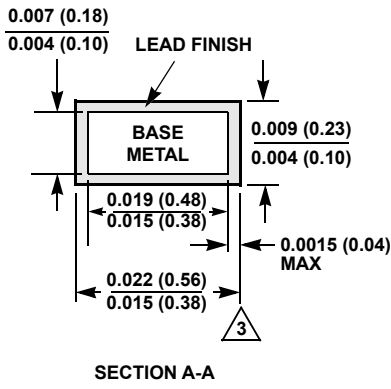
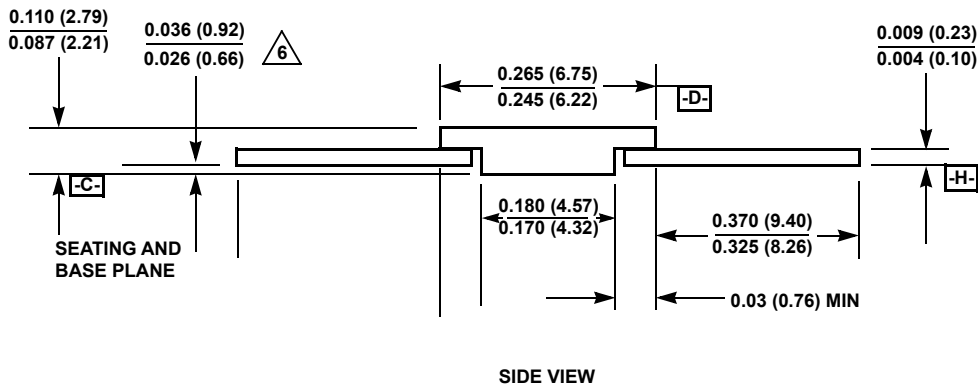
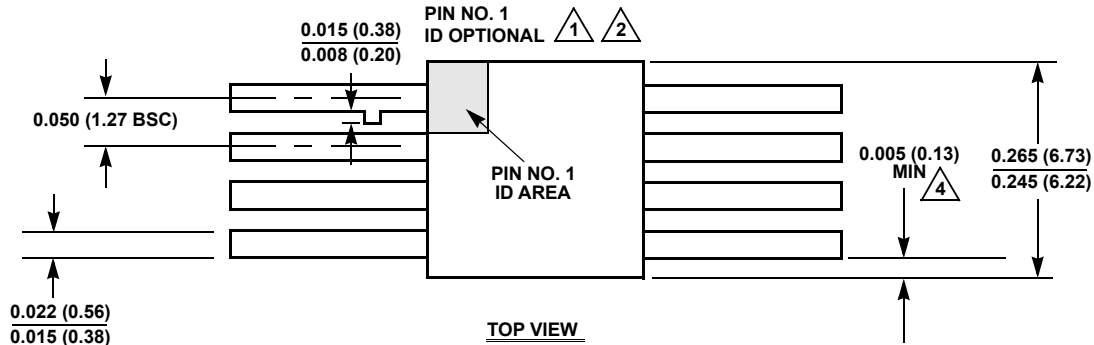
Package Outline Drawing

For the most recent package outline drawing, see [K8.A](#).

K8.A

8 LEAD CERAMIC METAL SEAL FLATPACK PACKAGE

Rev 4, 12/14



NOTES:

1. Index area: A notch or a pin one identification mark shall be located adjacent to pin one and shall be located within the shaded area shown. The manufacturer's identification shall not be used as a pin one identification mark. Alternately, a tab may be used to identify pin one.
2. If a pin one identification mark is used in addition to or instead of a tab, the limits of the tab dimension do not apply.
3. The maximum limits of lead dimensions (section A-A) shall be measured at the centroid of the finished lead surfaces, when solder dip or tin plate lead finish is applied.
4. Measure dimension at all four corners.
5. For bottom-brazed lead packages, no organic or polymeric materials shall be molded to the bottom of the package to cover the leads.
6. Dimension shall be measured at the point of exit (beyond the meniscus) of the lead from the body. Dimension minimum shall be reduced by 0.0015 inch (0.038mm) maximum when solder dip lead finish is applied.
7. Dimensioning and tolerancing per ANSI Y14.5M - 1982.
8. Controlling dimension: INCH.

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